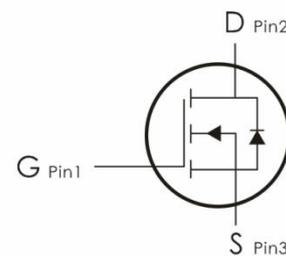
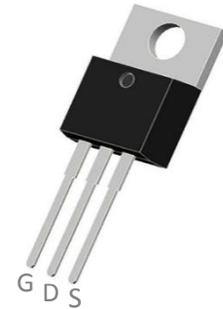


Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=100V, I_D=15A, R_{DS(ON)}<90m\ \Omega$ @ $V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C^3$	15	A
	Continuous Drain Current- $T_C=100^\circ C$	12	
P_D	Power Dissipation- $T_C=25^\circ C$	59	W
E_{AS}	Single pulse avalanche energy ⁵	6.1	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55-+150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.1	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62	$^\circ C/W$

Package Marking and Ordering Information:

Part NO.	Marking	Package
15N10	15N10	TO-220

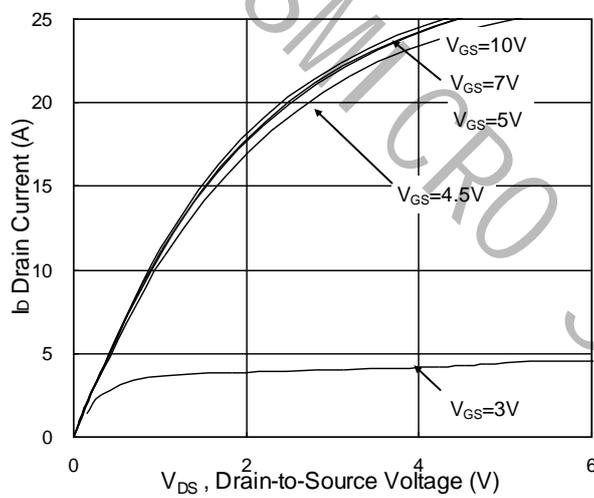
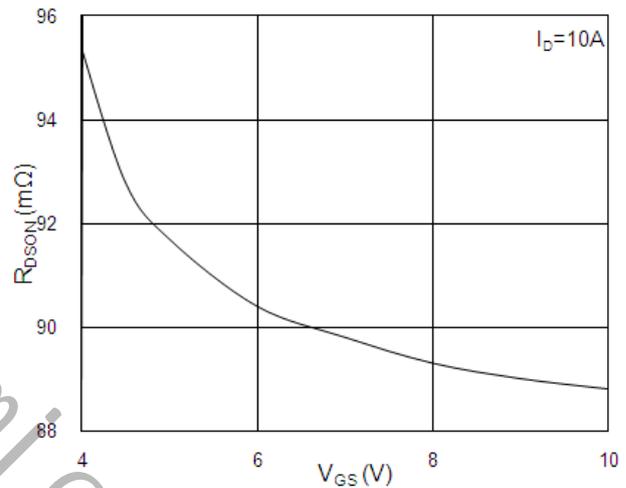
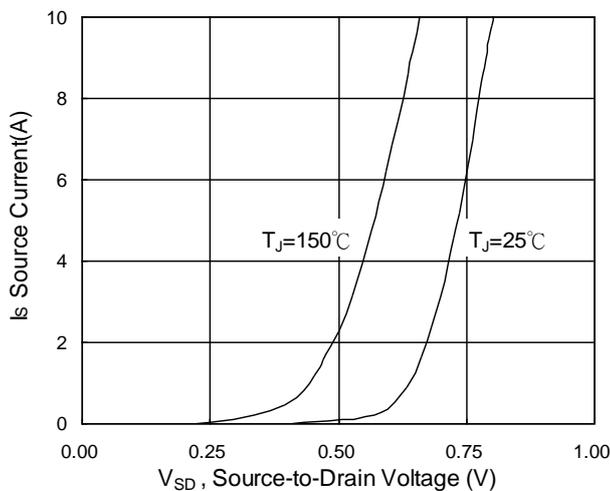
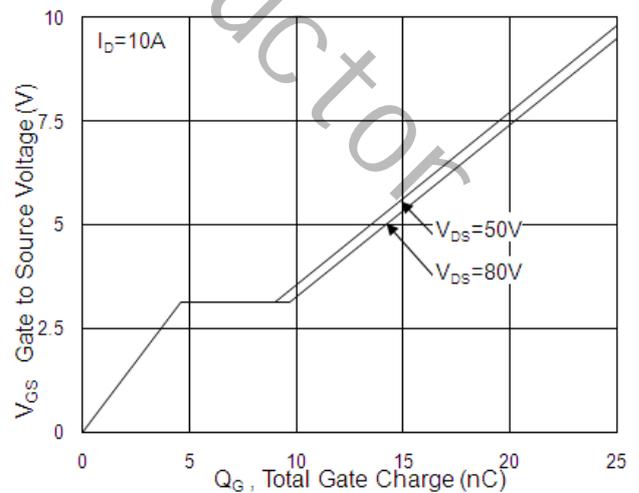
Electrical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=80V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1.5	---	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance ¹	$V_{GS}=10V, I_D=10A$	---	67	90	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance ²	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1535	---	pF
C_{oss}	Output Capacitance ²		---	60	--	
C_{rss}	Reverse Transfer Capacitance ²		---	37	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=50V, I_D=10A$ $R_G=3.3\ \Omega$	---	4.2	---	ns
t_r	Rise Time		---	8.2	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	35.6	---	ns
t_f	Fall Time		---	9.6	---	ns
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DS}=80V,$ $I_D=10A$	---	26.2	---	nC
Q_{gs}	Gate-Source Charge		---	4.6	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	5.1	---	nC
Drain-Source Diode Characteristics						
I_S	$V_G=V_D=0V^3$		---	---	15	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_D=1A$	---	---	1.2	V
T_{rr}	Reverse Recovery Time	$I_F=10A, V_{GS}=0V$	---	37	---	NS

Qrr	Reverse Recovery Charge	di/dt=100A/us	---	27.3	---	NC
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Notes:

- 1: Pulse test; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 2: Guaranteed by design, not subject to production testing.
- 3: Package limitation current is 10A.
- 4: Repetitive rating, pulse width limited by max junction temperature.
- 5: Starting $T_J = 25^\circ\text{C}$, $L = 0.1\text{mH}$, $I_{AS} = 11\text{A}$.

Typical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

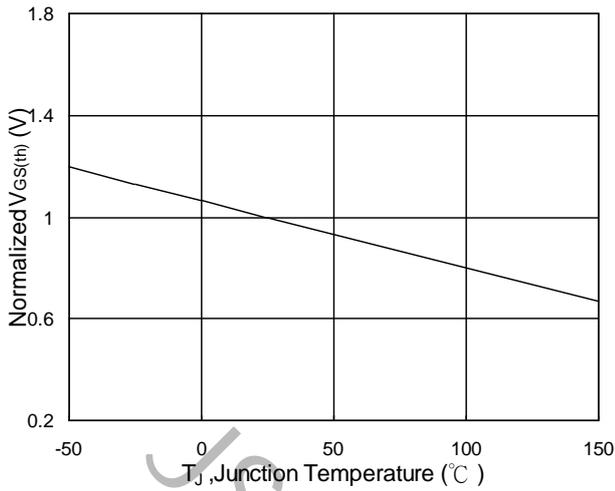


Fig.5 Normalized $V_{GS(th)}$ vs T_J

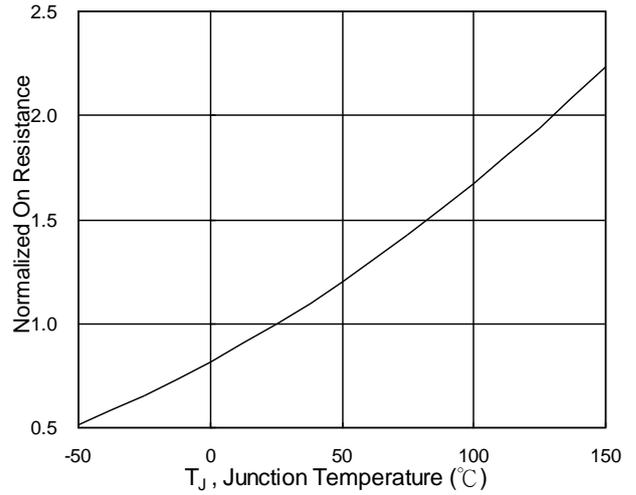


Fig.6 Normalized $R_{DS(on)}$ vs T_J

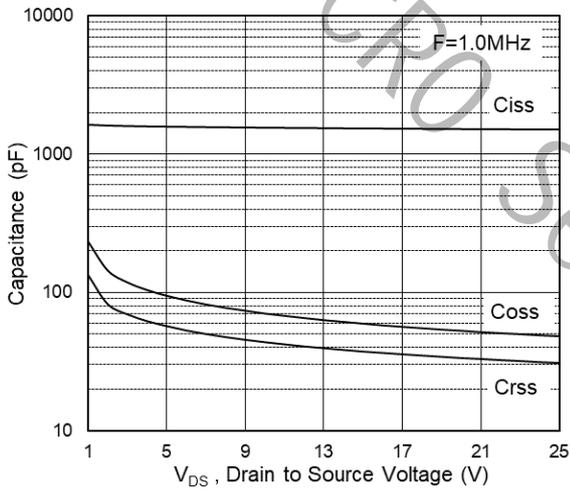


Fig.7 Capacitance

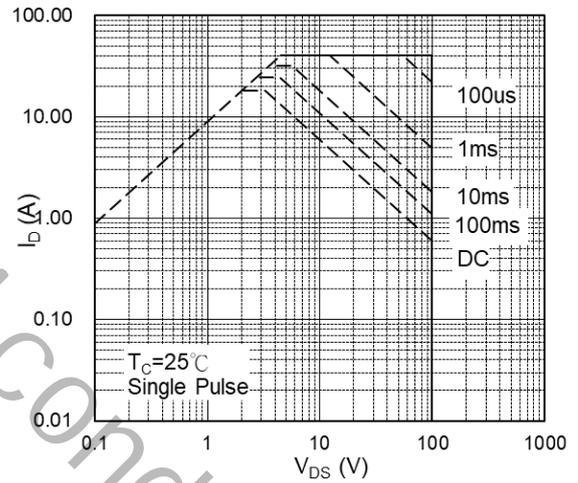


Fig.8 Safe Operating Area

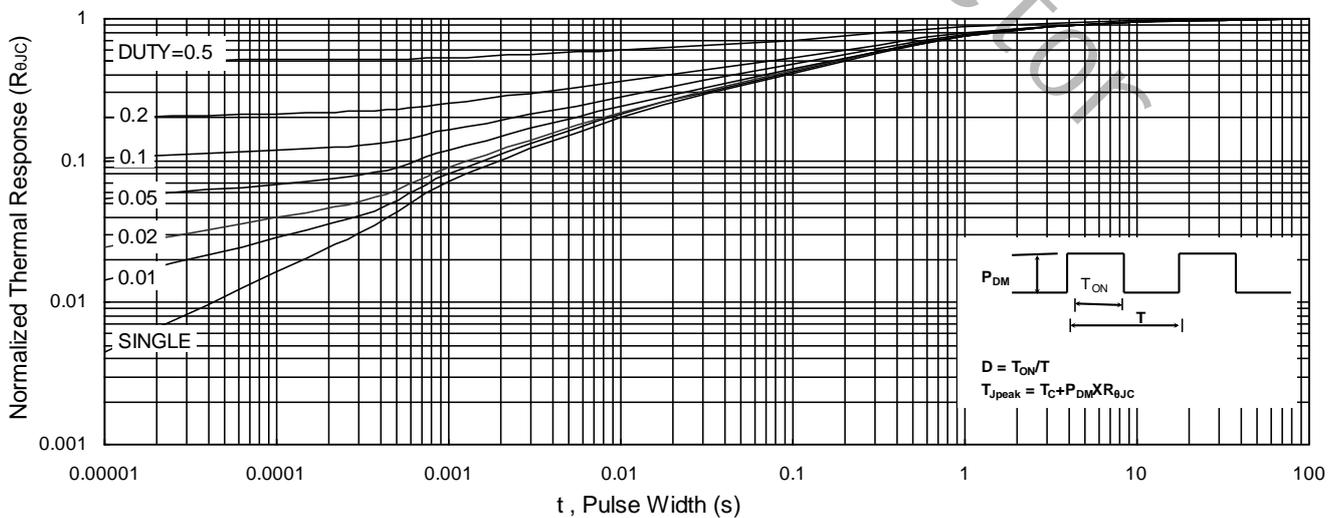


Fig.9 Normalized Maximum Transient Thermal Impedance

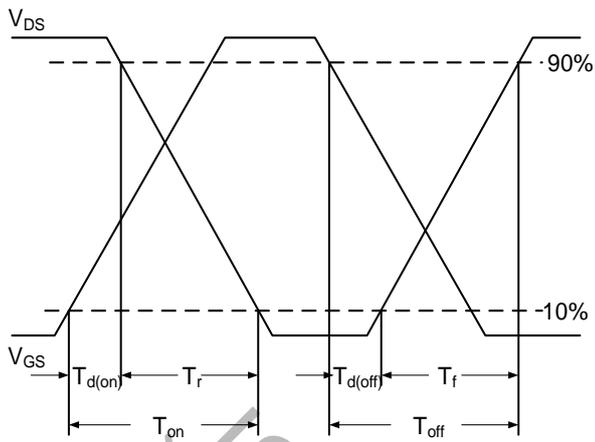


Fig.10 Switching Time Waveform

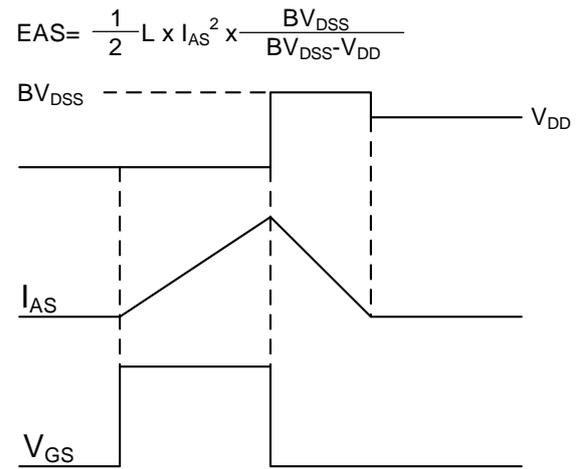


Fig.11 Unclamped Inductive Switching Waveform